

L Number	Hits	Search Text	DB	Time stamp
1	337	((synthetic same (sealing seal resin encapsulate encapsulation encapsuled encapsulating encase encased encasing)) and (bga ball bump (ball adj2 grid adj2 array))) and ( (trace pattern patterned patterning wiring metallization metal) and ((semiconductor die chip dice ic (integrated adj circuit)) and (bga ball bump (ball adj2 grid adj2 array)) and (substrate carrier board pcb ((printed circuit) adj3 board)) and ((center middle) with (bonding pad terminal electrode))))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/11/07 15:38
2	6454	(trace pattern patterned patterning wiring metallization metal) and ((semiconductor die chip dice ic (integrated adj circuit)) and (bga ball bump (ball adj2 grid adj2 array)) and (substrate carrier board pcb ((printed circuit) adj3 board)) and ((center middle) with (bonding pad terminal electrode)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/11/07 15:42